Technical Data Sheet

ASSEMBLY MATERIALS

Product Type: Conductive Adhesive
Product Name: PC 3201

Description
PC 3201 is a thermosetting, one-component, solvent-free, silver-filled epoxy conductive adhesive, designed for the connection of electronic (SMDs) and bare dies with ceramic substrates, PCB and lead frames. The glue has a hardener system, which includes a cationic curing agent.

Key Benefits
- Fast curing system, highly flexible
- High electrical and thermal conductivity
- Long processing time

Compliant Products
- Conductive Adhesive: PC3600 Series
- Non-conductive Adhesive: NCA 6, NCA 11

Applications
- Dispensing

Physical Properties

<table>
<thead>
<tr>
<th>Processing Life (days)</th>
<th>Curing Profile</th>
<th>Substrate and Components</th>
</tr>
</thead>
<tbody>
<tr>
<td>5</td>
<td>60 sec / 180 °C</td>
<td>Flex PCB, Flex lead frames and foils. Recommended surface: Ni/Au and Ag</td>
</tr>
<tr>
<td></td>
<td>3 min / 130 °C</td>
<td></td>
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</tbody>
</table>

<table>
<thead>
<tr>
<th>Adhesion (N/mm²)</th>
<th>Weight Loss during Curing Process at 150 °C (%)</th>
<th>Glass Transition Temperature (°C)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Standard: DIN EN 1465</td>
<td>Min. 4</td>
<td>Max. 0.8</td>
</tr>
<tr>
<td></td>
<td>Max. 0.8</td>
<td>Approx. 5.5</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Thermal Conductivity (W/mK)</th>
<th>Volume Resistivity (mΩ.cm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Min. 5</td>
<td>Max. 0.3</td>
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</table>

Halogen Content
Hydrolyse Halogen
Tolerance: Halogen < 50 ppm

Cleaning Instructions
The uncured adhesive can be removed with Zestron HC and other Zestron and Vigon cleaning materials. The cleaned parts must be completely dry before installing them in the machine. Defective components can be removed by heating the cured adhesive joint with hot air above 250°C. The hot remaining adhesive can be removed with a sharp tool.

Adhesive Conditioning
- Remove adhesive from freezer: Before opening the package leave it for at least 2 hours at room temperature so that adhesive heats up
- Do not open jar/cartridge while adhesive is cold to prevent condensation
- Do not use faster defrost systems
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Storage

- Store the adhesive in tightly-sealed containers and avoid exposure to high humidity and sunlight
- In cartridges: From the date of manufacture 12 months in a freezer at – 20 °C
- Store the cartridges with tip pointing downwards

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